



VMDSEMI

VUSA006R160NA

Datasheet



VMDSEMI

General Description

Symbol

$V_{(BR)DSS}$	$R_{DS(ON)_{max}}$	I_D
60V	16mΩ@10V	9A
	18mΩ@4.5V	

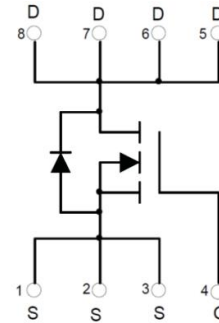


Figure 1 Symbol of VUSA006R160NA

Features

- High density cell design for ultra low $R_{DS(ON)}$
- Excellent package for good heat dissipation

Application

- Hard switched and high frequency circuits
- Power Switch Application
- Uninterruptible power supply

Package Type

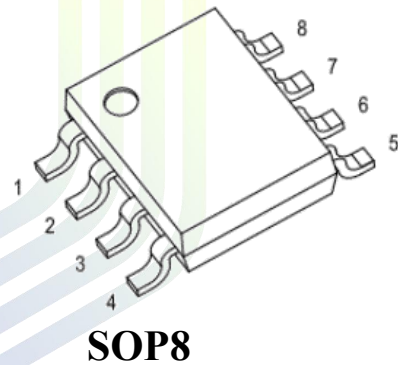


Figure 2 Package Type of VUSA006R160NA

Ordering Information

Product Name	Package
VUSA006R160NA	SOP8

Absolute Maximum Ratings ($T_A = 25\text{ }^\circ\text{C}$, unless otherwise specified)

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V_{DS}	60	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current ^{Note1}	I_D	9	A
Pulsed Drain Current ^{Note2}	I_{DM}	36	
Single Pulsed Avalanche Energy ^{Note6}	E_{AS}	16	mJ
Total Power Dissipation ^{Note4}	P_D	3.1	W
Junction Temperature	T_J	150	$^\circ\text{C}$
Storage Temperature	T_{STG}	-55 to 150	$^\circ\text{C}$

Thermal Resistance

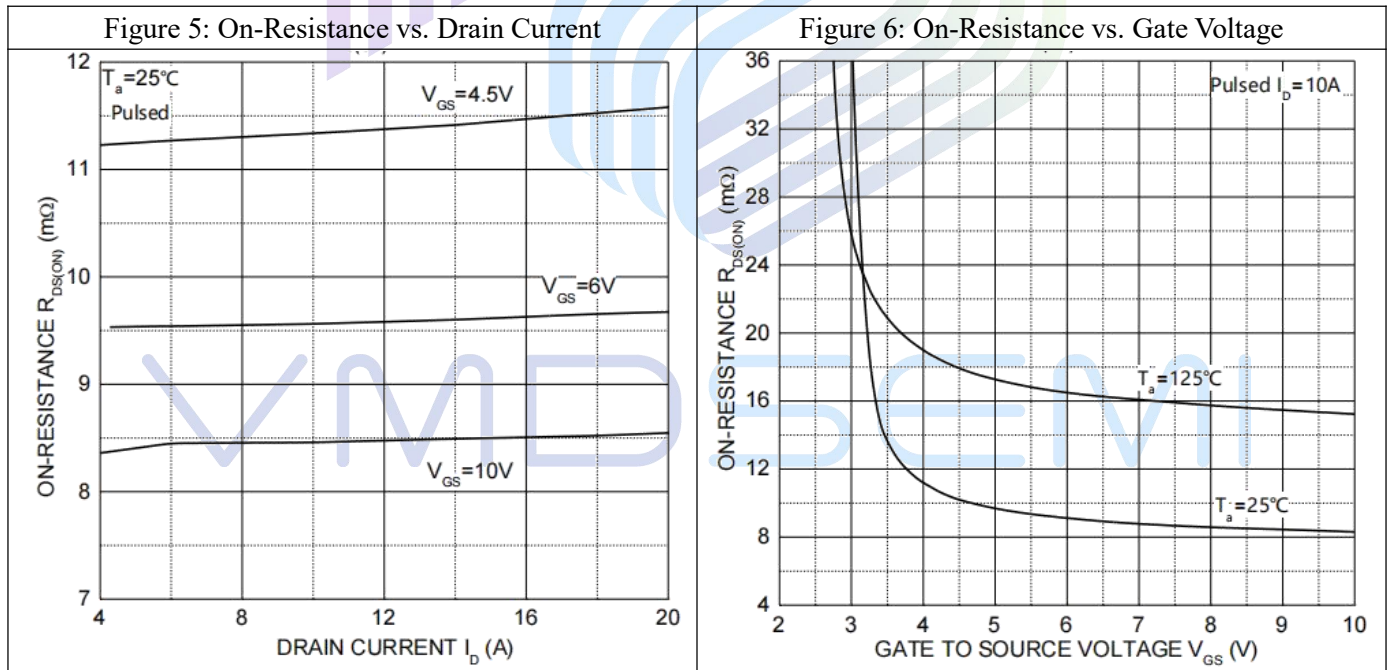
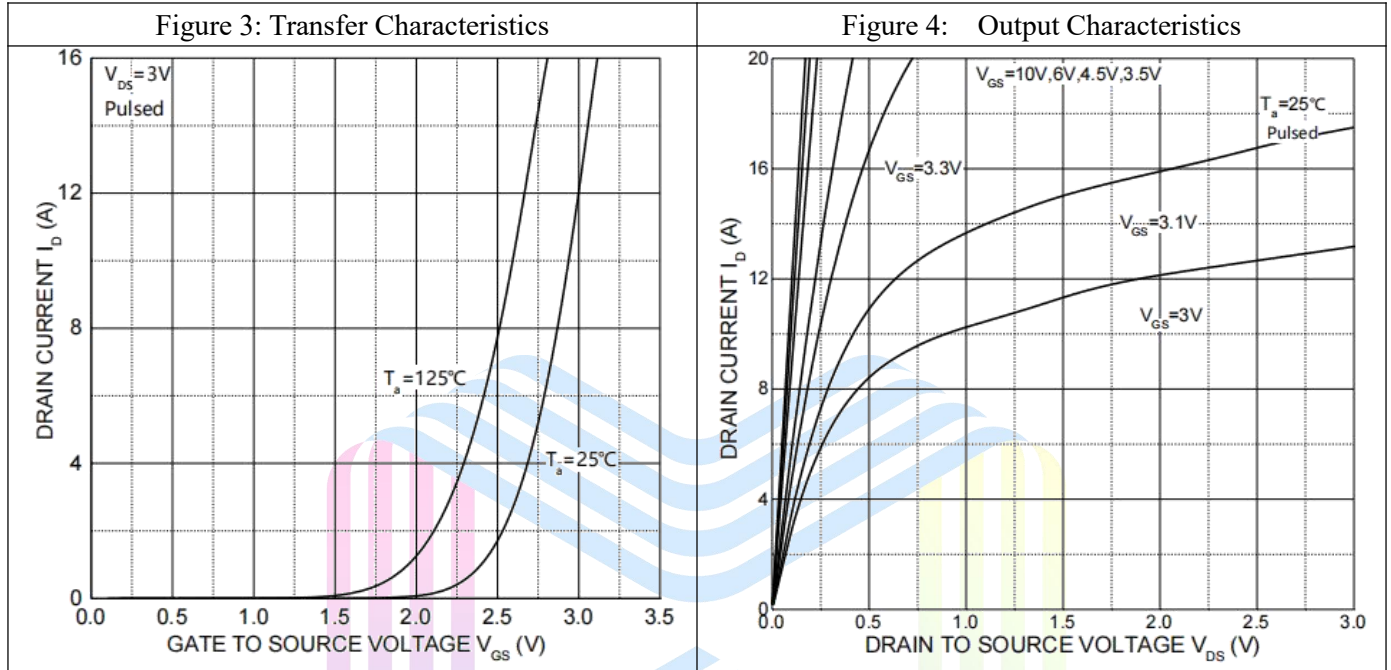
Parameter	Symbol	Min	Typ	Max	Unit
Thermal Resistance, Junction-to-Ambient ^{Note5} Stead State	$R_{\theta JA}$		65		$^\circ\text{C/W}$
Thermal Resistance, Junction-to-Ambient ^{Note5} $t \leq 10\text{S}$	$R_{\theta JA}$		40		$^\circ\text{C/W}$

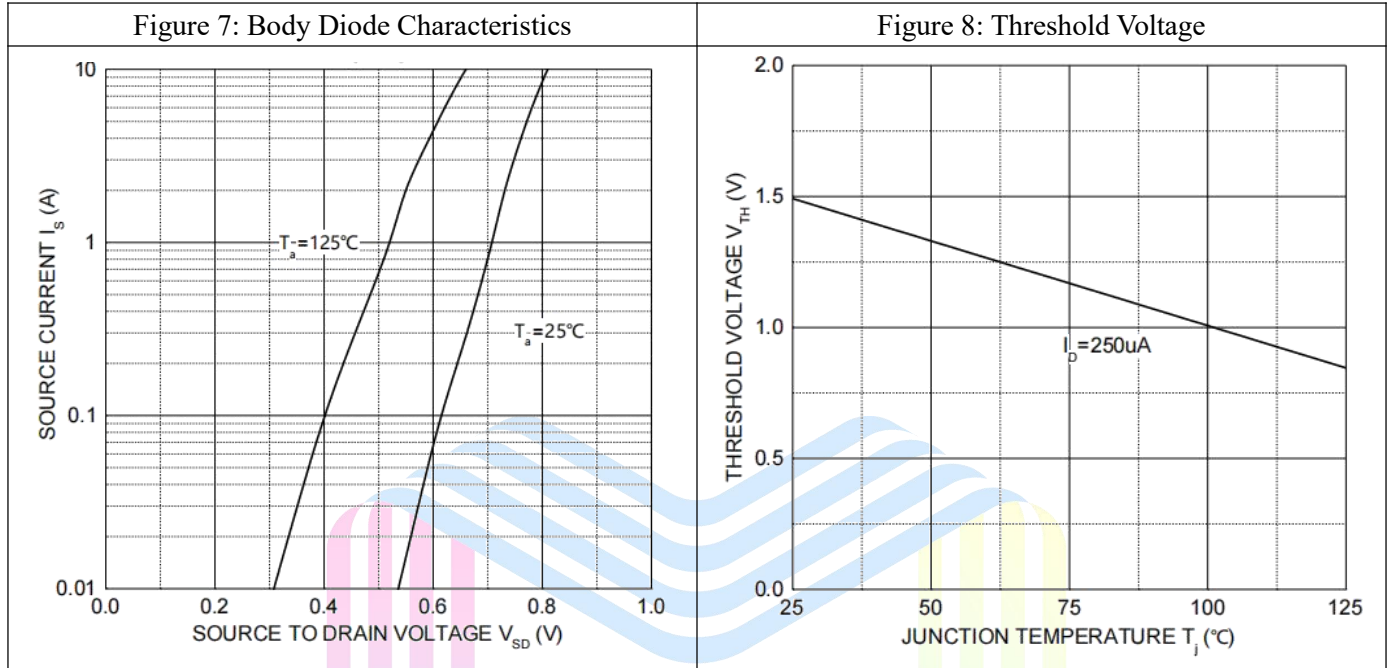
Electrical Characteristics ($T_A = 25\text{ }^\circ\text{C}$, unless otherwise specified)

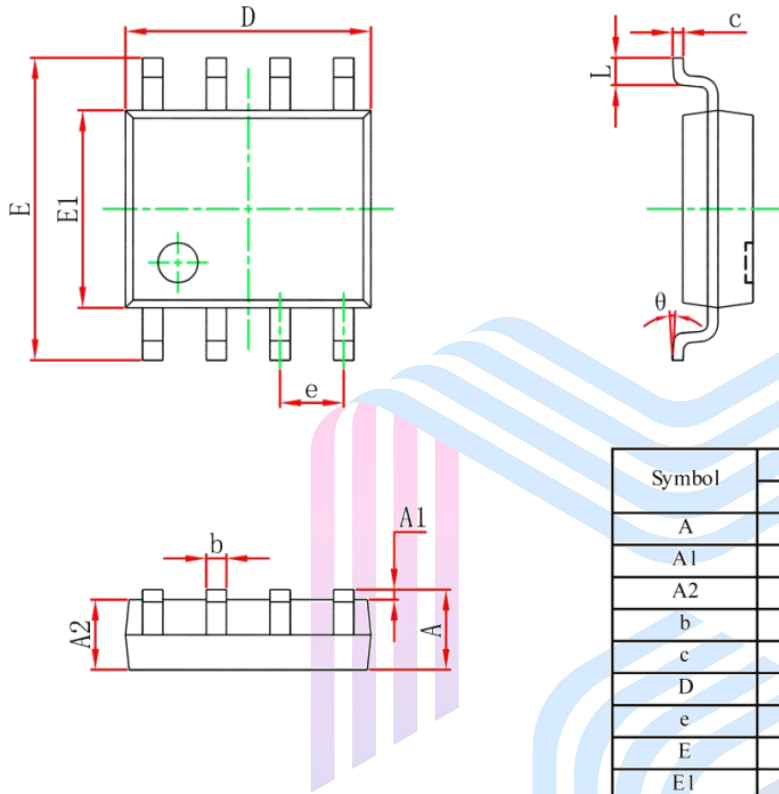
Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Statistic Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0V, I_D=250\mu A$	60			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=60V, V_{GS}=0V$			1	μA
Gate-Body Leakage Current	I_{GSS}	$V_{GS} = \pm 20V, V_{DS}=0V$			± 100	nA
Gate Threshold Voltage ^{Note3}	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	1	1.5	2.5	V
Static Drain-Source On-Resistance ^{Note3}	$R_{DS(on)}$	$V_{GS}=10V, I_D=9A$		8.7	16	mΩ
		$V_{GS}=4.5V, I_D=9A$		11.5	18	
Forward Transconductance ^{Note3}	g_{FS}	$V_{DS}=5V, I_D=9A$	10	20		S
Dynamic Characteristics						
Input Capacitance	C_{ISS}	$V_{DS}=30V$		2595		pF
Output Capacitance	C_{OSS}	$V_{GS}=0V$		177		pF
Reverse Transfer Capacitance	C_{RSS}	$f=1MHz$		163		pF
Total Gate Charge	Q_g	$V_{DS}=30V$		62		nC
Gate-Source Charge	Q_{gs}	$V_{GS}=10V$		10		
Gate-Drain Charge	Q_{gd}	$I_D=8A$		21		
Gate Resistance	R_g	$f=1MHz, \text{Open drain}$		2		Ω
Switching Parameters						
Turn-on Delay Time	$t_{d(on)}$	$V_{DD}=30V$		9.5		ns
Turn-on Rise Time	t_r	$V_{GS}=10V$		7		
Turn-off Delay Time	$t_{d(off)}$	$R_L=3\Omega$		35		
Turn-off Fall Time	t_f	$R_G=3\Omega$		6		
Diode Characteristics						
Diode Forward Voltage ^{Note3}	V_{SD}	$V_{GS}=0V, I_S=9A$			1.2	V

Notes :

- 1.The maximum current rating is limited by package.And device mounted on a large heatsink.
- 2.Pulse Test : Pulse Width $\leq 10\mu s$, duty cycle $\leq 1\%$.
- 3.Pulse Test : Pulse Width $\leq 380\mu s$, duty cycle $\leq 2\%$.
- 4.The power dissipation P_D is limited by $T_{J(MAX)} = 150^\circ\text{C}$.And device mounted on a large heatsink
- 5.Device mounted on 1in2 FR-4 board with 2oz. Copper, in a still air environment with $T_A = 25^\circ\text{C}$.
- 6.EAS Test Condition $V_{DD} = 15V, V_{GS} = 10V, L = 0.1mH, I_{AS} = 18A$

Typical Performance Characteristics





Mechanical Dimensions:
SOP8 Package Information


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.007	0.010
D	4.800	5.000	0.189	0.197
e	1.270 (BSC)		0.050 (BSC)	
E	5.800	6.200	0.228	0.244
E1	3.800	4.000	0.150	0.157
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°

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Via-Media Semiconductor Limited Company

<http://www.vmdsemi.com>

Main Sites:

- Headquarters

Hangzhou Via-Media Semiconductor Co., LTD.
1305-1306, Building 71, No. 90, Wensan Road, Xihu
District, Hangzhou, Zhejiang Province, P.R. China
Tel: +86-0571-8515 0563

- Chengdu Office

Chengdu Winhi Semiconductor Co., LTD.
Floor 15, Building 5, No. 171, Hele 2nd Street,
Chengdu, Sichuan Province, P.R. China
Tel: +86-028-8505 0771

- Shanghai

Shanghai R&D Center.
1506~1508, Xinyin Building, 888 Yishan Road,
Shanghai, P.R of China
Tel: +86- 021-54201999

- Shenzhen

Shenzhen Sales office
Room 4A15, Block AB, Tianxiang Building,
Chegongmiao , Futian District, Shenzhen, P.R of China
Tel: +86-0755- 82570682

- Xi'an

Xi'an R&D Center
1703B, Building A, Greenland Center, Jinye Road,
High-Tech Zone, Xi'an, Shaanxi, P.R of China